



DATE: 5th January, 2018

PCN #: 2304

PCN Title: Additional Qualified Fab Source for MOSFET Devices and BOM (Bill of Materials) on Selected Devices

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE

PCN-2304 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
5 th January, 2018	5 th April, 2018	Analog Semiconductors	Additional FAB and BOM	2304
TITLE				
Additional Qualified Fab Source for MOSFET Devices and BOM (Bill of Materials) on Selected Devices				
DESCRIPTION OF CHANGE				
This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes has qualified additional Fab source (SFAB) for MOSFET devices, and BOM (Bill of Materials) on selected devices. Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure there is no change to device functionality or electrical specifications in the datasheet. See attached (embedded) qualification/reliability report.				
IMPACT				
Continuity of Supply. No change in data sheet parameters and/or product performance.				
PRODUCTS AFFECTED				
Please see the part list below in the following Tables: Table 1 - Add additional die DN008B0-2 (from SFAB) Diodes FAB located in Shanghai, China as 2nd MOSFET die source Table 2 - Add additional die DN027A0 (from SFAB) Diodes FAB located in Shanghai, China as 2nd MOSFET die source Table 3 - LDF change from SOT23U to SOT23Z. Epoxy changed from non-conductive ABP8611 to conductive 84-1LMISR4 Table 4 - Lead Frame change from EFTEC-64T to CDA194, Molding Compound change from CEL-1702HF9 SK to CEL-1700HF4OSK-D3				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	http://www.diodes.com/contacts			
Data Sheet:	http://www.diodes.com/products			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1 - Add additional die DN008B0-2 (from SFAB) as 2nd MOSFET die source

AL1697-20CS7-13					
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Table 2 - Add additional die DN027A0 (from SFAB) as 2nd MOSFET die source

AL1692-30BS7-13	AL1692L-30BS7-13				
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Table 3 - LDF change from SOT23U to SOT23Z. Epoxy changed from non-conductive ABP8611 to conductive 84-1LMISR4

ZXRE330ASA-7	ZXRE330ESA-7				
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Table 4 - Lead Frame change from EFTEC-64T to CDA194 , Compound change from CEL-1702HF9 SK to CEL-1700HF4OSK-D3

AP2552W6-7	AP2552AW6-7	AP2553W6-7	AP2553AW6-7		
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